

- 1 -

JP Application No. 2000-184046

[Name of Document] ABSTRACT

[Abstract]

[Object] To provide an RF module which can have a reduced size.

[Solving Means] An RF module 10 has a multi-layered substrate 12. A BBIC 14, a memory IC 16, a quartz oscillator 18 and surface-mount components 20 are mounted on the upper side of the multi-layered substrate 12. A metallic cap 22 also is attached to the upper side of the multi-layered substrate 12. A cavity 24 is formed in the lower side of the multi-layered substrate 12 substantially at the center thereof. A first RFIC 26 and a second RFIC 28 are embedded in the cavity 24. Wiring patterns 32 for connection between the BBIC 14 and the memory IC 16, through-holes 34, RF passive components 36, and shield ground electrode pattern 38 are formed internally of the multi-layered substrate 12.

[Selected Figure] Fig. 1